

	Type	Hits	Search Text	DBs
18	BRS	2	5853622.URPN. ("2993815"   "3256109"   "3410714"   "3502609"   "3679439"   "3681135"   "3714709"   "3791027"   "3800020"   "3801364"   "3808046"   "3857798"   "3904555"   "3960777"   "3983075"   "4000016"   "4001146"   "4127699"   "4147669"   "4186036"   "4233103"   "4273593"   "4278702"   "4293451"   "4327124"   "4352899"   "4353816"   "4368281"   "4396666"   "4400214"   "4415486"   "4429657"   "4434084"   "4457861"   "4459166"   "4496475"   "4533685"   "4557857"   "4564563"   "4575432"   "4578425"   "4581158"   "4592861"   "4639396"   "4652398"   "4673532"   "4678602"   "4680141"   "4683653"   "4696764"   "4705647"   "4731130"   "4732702"   "4733018"   "4740252"   "4756756"   "4765929"   "4775500"   "4780371"   "4786437"   "4789411"   "4803543"   "4808434"   "4816184"   "4820446"   "4830779"   "4836955"   "4859268"   "4872928"   "4874548"   "4880570"   "4882227"   "4888135"   "4894184"   "4940498"   "4971727"   "4996005"   "5088189"   "5136365"   "5376403"   "5463190").PN.	USPAT
19	BRS	81		USPAT
20	BRS	1427383	(circui adj board) or (wiring adj boared) or (substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
21	BRS	2459	((circui adj board) or (wiring adj boared) or (substrate)) and aramid	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
22	BRS	5773	((circui adj board) or (wiring adj boared) or (substrate)) and (conductive adj paste)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
23	BRS	393821	((circui adj board) or (wiring adj boared) or (substrate)) and (via\$1 or hole\$1 or aperture\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
24	BRS	190	((circui adj board) or (wiring adj boared) or (substrate)) and (transient adj liquid)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
25	BRS	24	((circui adj board) or (wiring adj boared) or (substrate)) and (transient near3 sinter\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
26	BRS	3	5948533.URPN.	USPAT
27	BRS	71	("3541222"   "3791858"   "3835531"   "3939559"   "3953924"   "3971610"   "4075757"   "4159222"   "4273593"   "4285780"   "4306925"   "4331286"   "4332341"   "4383363"   "4446477"   "4478882"   "4519760"   "4634631"   "4640866"   "4642160"   "4645733"   "4647508"   "4661204"   "4667220"   "4685210"   "4692839"   "4702792"   "4755911"   "4788766"   "4810332"   "4816323"   "4818728"   "4841355"   "4849284"   "4864722"   "4868350"   "4874721"   "4875617"   "4897338"   "4902606"   "4908940"   "4915983"   "4921777"   "4922377"   "4926241"   "4954313"   "4958258"   "4967314"   "4995941"   "5008997"   "5010641"   "5023921"   "5030499"   "5031308"   "5046238"   "5049974"   "5055425"   "5061548"   "5072075"   "5097393"   "5129142"   "5274912"   "5276955"   "5309629"   "5329695"   "5376403"   "5440805"   "5498467"   "5538789"   "5703405"   "5716663").PN.	USPAT
28	BRS	108	((circui adj board) or (wiring adj boared) or (substrate)) and (via\$1 or hole\$1 or aperture\$1)) and (((circui adj board) or (wiring adj boared) or (substrate)) and (transient adj liquid))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
29	BRS	3341	(((circui adj board) or (wiring adj boared) or (substrate)) and (conductive adj paste)) and (((circui adj board) or (wiring adj boared) or (substrate)) and (via\$1 or hole\$1 or aperture\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
30	BRS	15004	((circui adj board) or (wiring adj boared) or (substrate)) and (heat adj sink)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
31	BRS	215	((((circui adj board) or (wiring adj boared) or (substrate)) and (conductive adj paste)) and (((circui adj board) or (wiring adj boared) or (substrate)) and (via\$1 or hole\$1 or aperture\$1))) and (((circui adj board) or (wiring adj boared) or (substrate)) and (heat adj sink))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
32	BRS	8919	(((circui adj board) or (wiring adj boared) or (substrate)) and (heat adj sink)) and (((circui adj board) or (wiring adj boared) or (substrate)) and (via\$1 or hole\$1 or aperture\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
33	BRS	2498	((((circui adj board) or (wiring adj boared) or (substrate)) and (heat adj sink)) and (((circui adj board) or (wiring adj boared) or (substrate)) and (via\$1 or hole\$1 or aperture\$1))) and (cavity or	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
34	BRS	2352	((((((circui adj board) or (wiring adj boared) or (substrate)) and (heat adj sink)) and (((circui adj board) or (wiring adj boared) or (substrate)) and (via\$1 or hole\$1 or aperture\$1))) and (cavity or cavities)) and cavity	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
35	BRS	1422	((((((circui adj board) or (wiring adj boared) or (substrate)) and (heat adj sink)) and (((circui adj board) or (wiring adj boared) or (substrate)) and (via\$1 or hole\$1 or aperture\$1))) and (cavity or cavities)) and cavity) and (chip or IC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
36	BRS	488	((((((circui adj board) or (wiring adj boared) or (substrate)) and (heat adj sink)) and (((circui adj board) or (wiring adj boared) or (substrate)) and (via\$1 or hole\$1 or aperture\$1))) and (cavity or cavities)) and cavity) and (chip or IC)) and (multi-layer or multilayer or multi adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB